R1, R2, and R3 form 3dB pad by default.

NOTES:
1) DNI = DO NOT INSTALL

Schematic default is DAC38RF83. Install R239 and R240 for DAC38RF80.
NOTES:
Schematic default is DAC38RF83.
For DAC38RF80:
Install R238, R241
DNI C179, C400, L9, L10, T5, T7, C330, C331, C332,  
C401, C403, C404, C328, C327, C399, R273,  
C398, C397, J6
Make sure this line does not hold LMK high before LMK can be programmed for SDO.
NOTES:
To bypass LDO U37: Install R298, R121, R122
DNI R221, R296, R284

To use LDO U34 (U35 output = 2.5V): DNI R330
Install R227

POWER SUPPLIES +.9V, +1.8V
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